

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

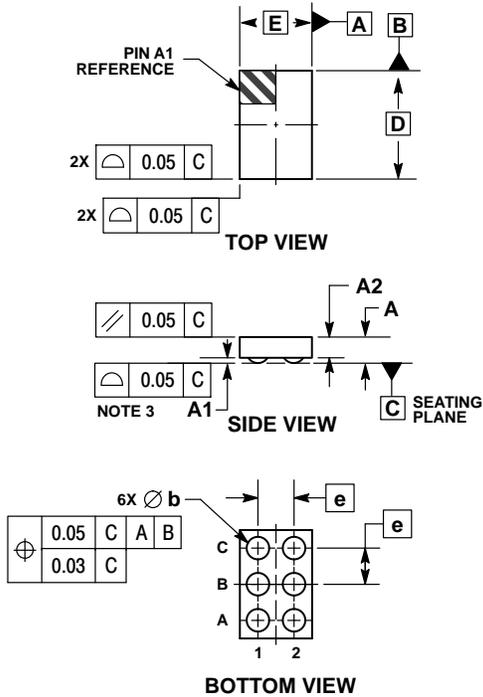
ON Semiconductor®




SCALE 4:1

WLCSP6, 1.20x0.80
CASE 567MV
ISSUE B

DATE 05 JUN 2018



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	—	0.33
A1	0.04	0.08
A2	0.23 REF	
b	0.24	0.30
D	1.20 BSC	
E	0.80 BSC	
e	0.40 BSC	

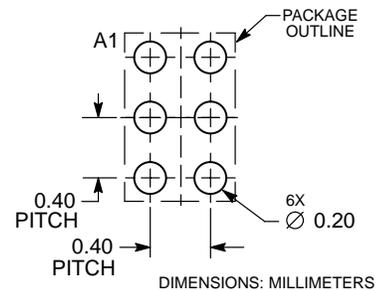
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP6, 1.20x0.80	PAGE 1 OF 1

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